



**Advanced Power
Electronics Corp.**

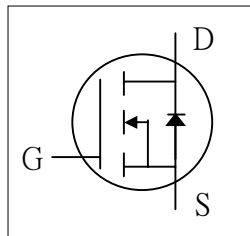
AP04N70BP-A

Pb Free Plating Product

N-CHANNEL ENHANCEMENT MODE

POWER MOSFET

- ▼ Dynamic dv/dt Rating
- ▼ Repetitive Avalanche Rated
- ▼ Fast Switching
- ▼ Simple Drive Requirement
- ▼ RoHS Compliant

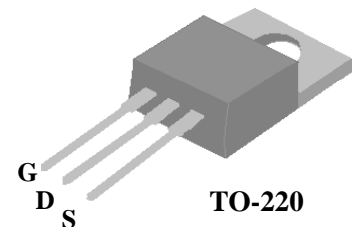


BV_{DSS}	650V
$R_{DS(ON)}$	2.4 Ω
I_D	4A

Description

AP04N70 series are specially designed as main switching devices for universal 90~265VAC off-line AC/DC converter applications. TO-220 type provide high blocking voltage to overcome voltage surge and sag in the toughest power system with the best combination of fast switching, ruggedized design and cost-effectiveness.

The TO-220 package is universally preferred for all commercial-industrial applications. The device is suited for switch mode power supplies, DC-AC converters and high current high speed switching circuits.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	650	V
V_{GS}	Gate-Source Voltage	± 30	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	4	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	2.5	A
I_{DM}	Pulsed Drain Current ¹	15	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	62.5	W
	Linear Derating Factor	0.5	W/ $^\circ C$
E_{AS}	Single Pulse Avalanche Energy ²	100	mJ
I_{AR}	Avalanche Current	4	A
E_{AR}	Repetitive Avalanche Energy	4	mJ
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Thermal Resistance Junction-case	Max. 2	$^\circ C/W$
Rthj-a	Thermal Resistance Junction-ambient	Max. 62	$^\circ C/W$

Data & specifications subject to change without notice

200712051-1/6



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Electrical Characteristics @ $T_J=25^{\circ}\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=1mA$	650	-	-	V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	Reference to $25^{\circ}\text{C}, I_D=1mA$	-	0.6	-	$V/^{\circ}\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=2A$	-	-	2.4	Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2	-	4	V
g_{fs}	Forward Transconductance	$V_{DS}=10V, I_D=2A$	-	2.5	-	S
I_{DSS}	Drain-Source Leakage Current ($T_J=25^{\circ}\text{C}$)	$V_{DS}=600V, V_{GS}=0V$	-	-	10	μA
	Drain-Source Leakage Current ($T_J=150^{\circ}\text{C}$)	$V_{DS}=480V, V_{GS}=0V$	-	-	100	μA
I_{GSS}	Gate-Source Leakage	$V_{GS}=\pm 30V$	-	-	± 100	nA
Q_g	Total Gate Charge ³	$I_D=4A$	-	16.7	-	nC
Q_{gs}	Gate-Source Charge	$V_{DS}=480V$	-	4.1	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$V_{GS}=10V$	-	4.9	-	nC
$t_{d(on)}$	Turn-on Delay Time ³	$V_{DD}=300V$	-	11	-	ns
t_r	Rise Time	$I_D=4A$	-	8.3	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=10\Omega, V_{GS}=10V$	-	23.8	-	ns
t_f	Fall Time	$R_D=75\Omega$	-	8.2	-	ns
C_{iss}	Input Capacitance	$V_{GS}=0V$	-	950	-	pF
C_{oss}	Output Capacitance	$V_{DS}=25V$	-	65	-	pF
C_{rss}	Reverse Transfer Capacitance	$f=1.0MHz$	-	6	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
I_S	Continuous Source Current (Body Diode)	$V_D=V_G=0V, V_S=1.5V$	-	-	4	A
I_{SM}	Pulsed Source Current (Body Diode) ¹		-	-	15	A
V_{SD}	Forward On Voltage ³	$T_J=25^{\circ}\text{C}, I_S=4A, V_{GS}=0V$	-	-	1.5	V

Notes:

1. Pulse width limited by safe operating area.
2. Starting $T_J=25^{\circ}\text{C}$, $V_{DD}=50V$, $L=25mH$, $R_G=25\Omega$, $I_{AS}=4A$.
3. Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

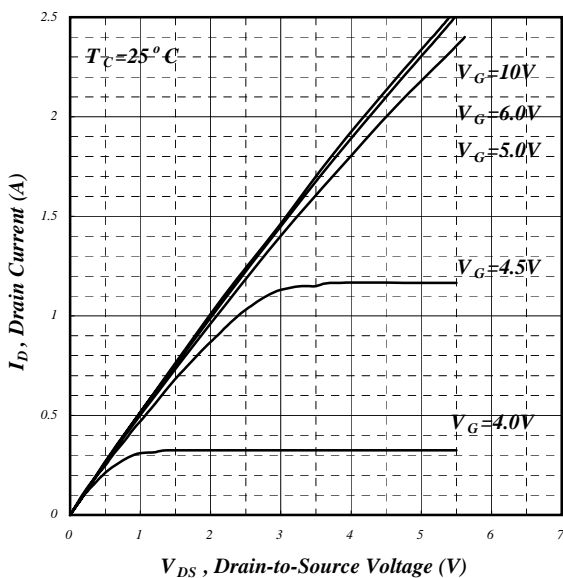


Fig 1. Typical Output Characteristics

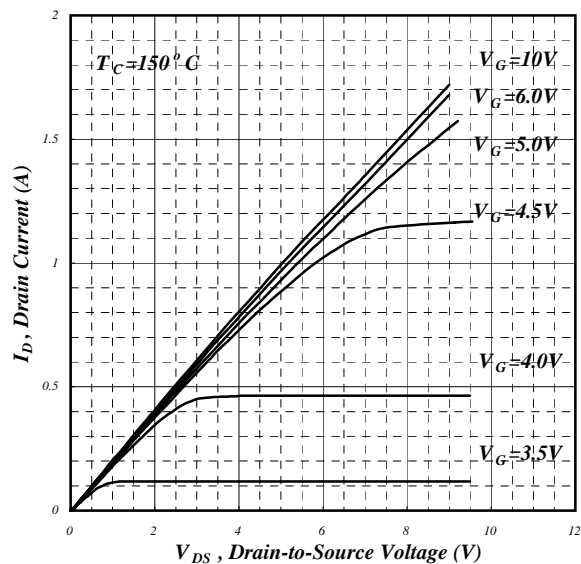


Fig 2. Typical Output Characteristics

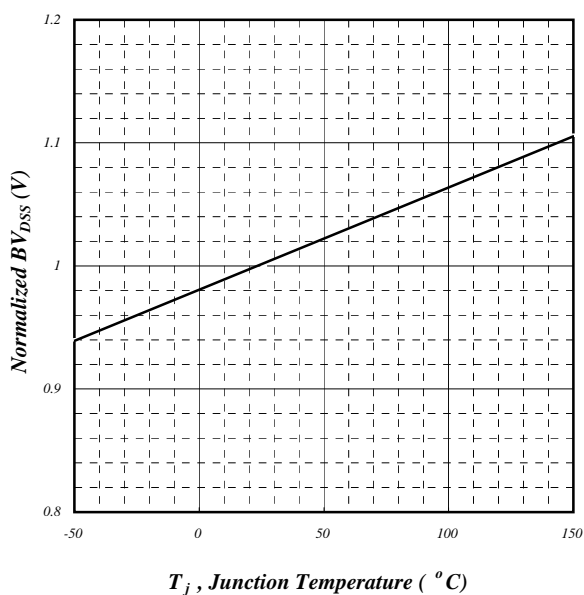


Fig 3. Normalized BV_{DSS} v.s. Junction Temperature

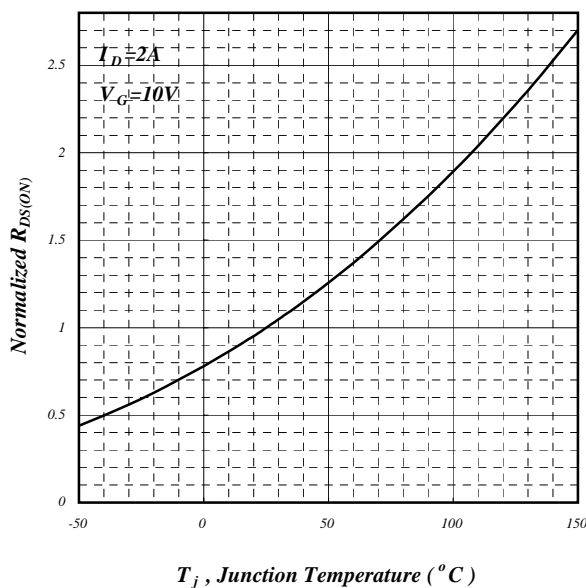


Fig 4. Normalized On-Resistance v.s. Junction Temperature



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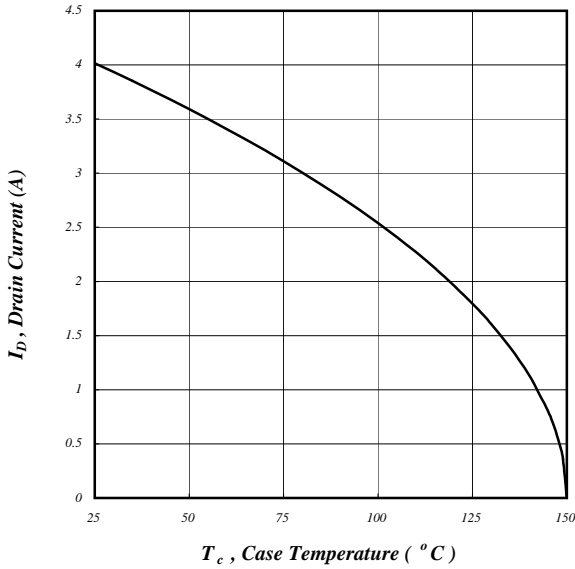


Fig 5. Maximum Drain Current v.s. Case Temperature

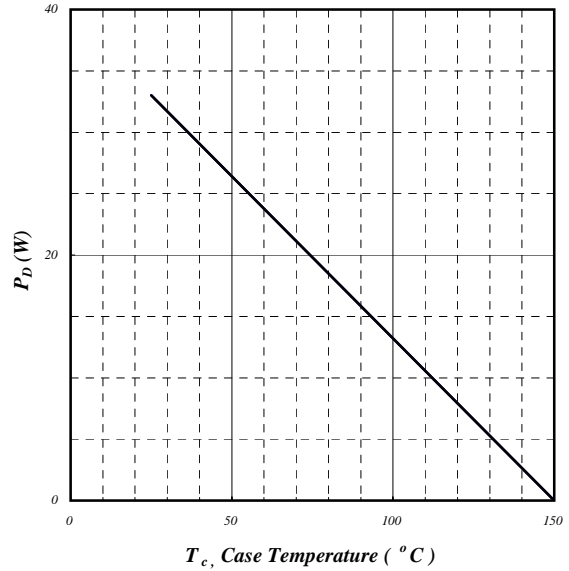


Fig 6. Typical Power Dissipation

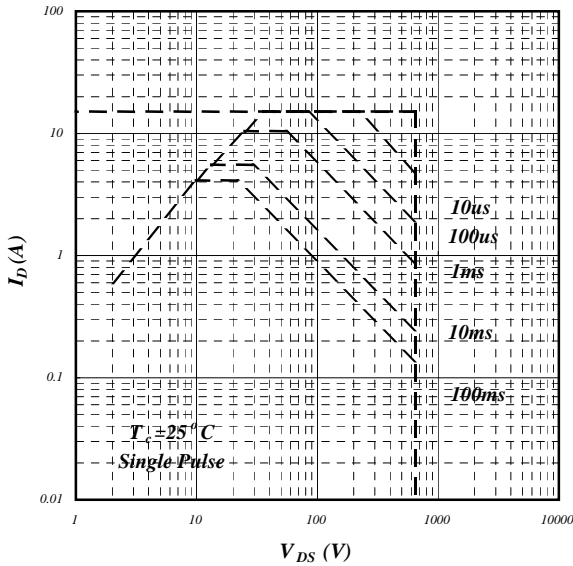


Fig 7. Maximum Safe Operating Area

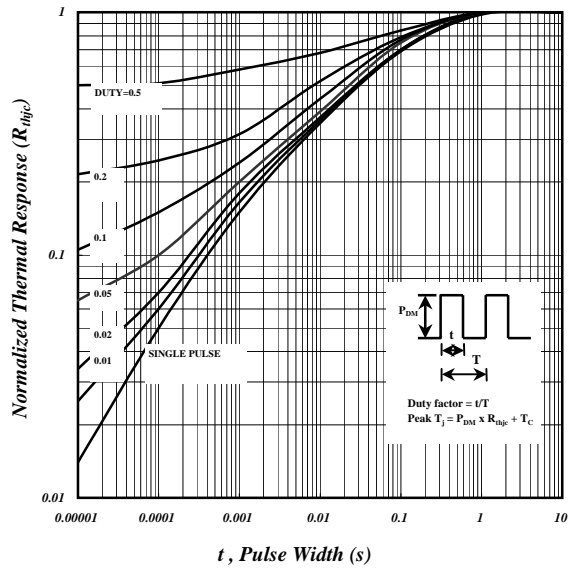


Fig 8. Effective Transient Thermal Impedance



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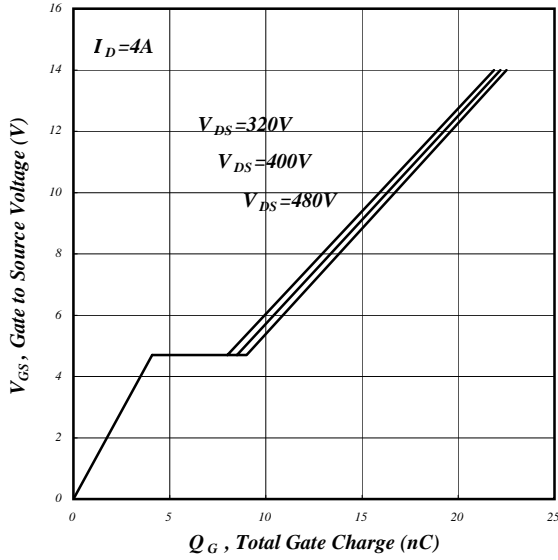


Fig 9. Gate Charge Characteristics

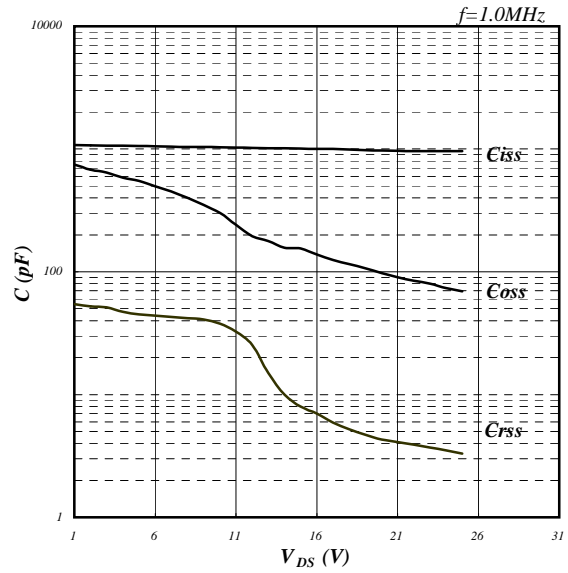


Fig 10. Typical Capacitance Characteristics

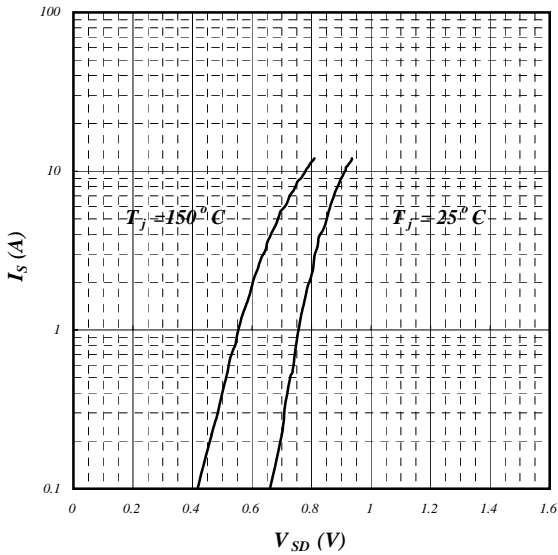


Fig 11. Forward Characteristic of Reverse Diode

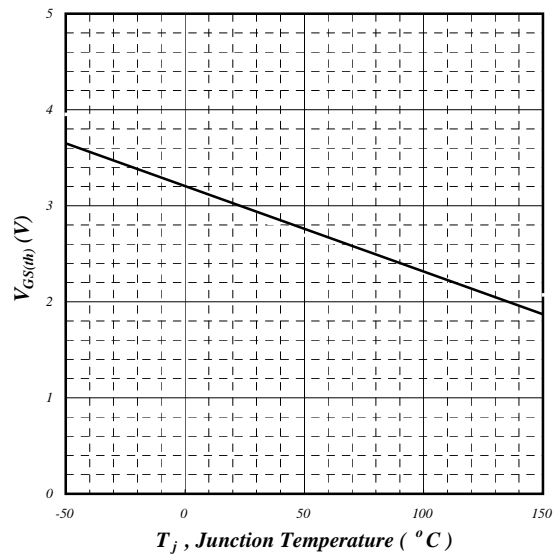


Fig 12. Gate Threshold Voltage v.s. Junction Temperature



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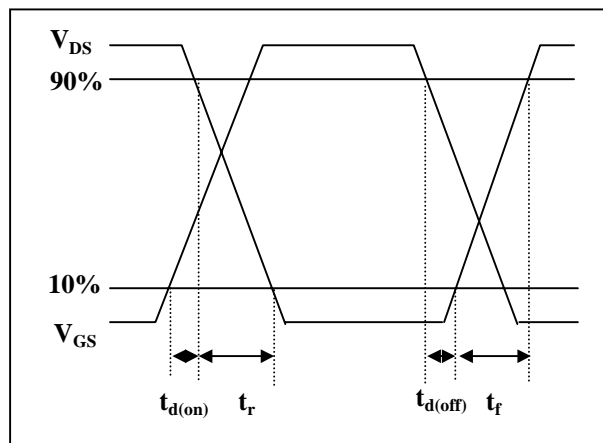
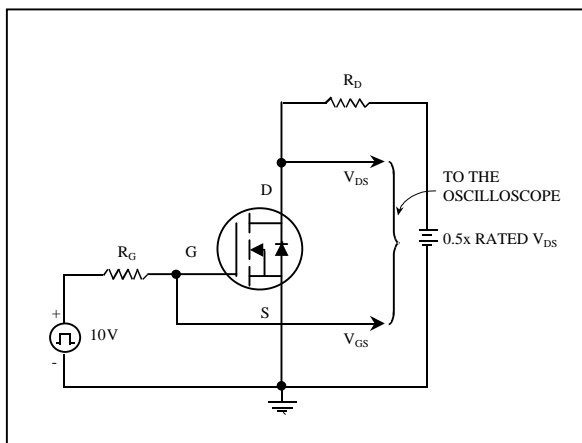


Fig 13. Switching Time Circuit

Fig 14. Switching Time Waveform

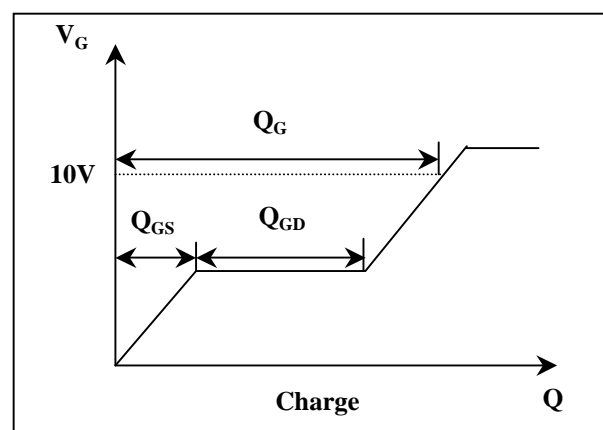
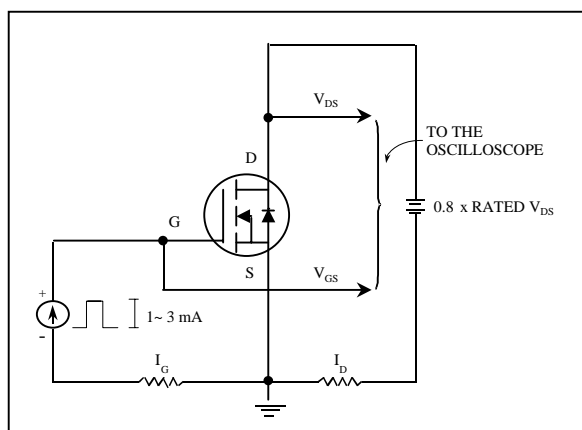


Fig 15. Gate Charge Circuit

Fig 16. Gate Charge Waveform